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- (71) **Applicant:** **AKRIBIS SYSTEMS PTE LTD** [SG/SG];
Blk 5012 TechPlace II #01-05 Ang Mo Kio Avenue 5, Singapore 569876 (SG).
- (72) **Inventors:** **CHANTAGORN, Udornpan**; c/o Blk 5012 TechPlace II #01-05 Ang Mo Kio Avenue 5, Singapore 569876 (SG). **KIATTIPHONG, Paiboonsuk**; c/o Blk 5012 TechPlace II #01-05 Ang Mo Kio Avenue 5, Singapore 569876 (SG). **LEOW, Yong Peng**; c/o Blk 5012 TechPlace II #01-05 Ang Mo Kio Avenue 5, Singapore 569876 (SG).
- (74) **Agent:** **CHONG, Yoke Fooi**; c/o W. P. Lai & Company, P. O. Box 0399, PSA Building, Singapore 911144 (SG).
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- (54) **Title:** WORKPIECE EJECTING SYSTEM FOR USE IN STAMPING MACHINE

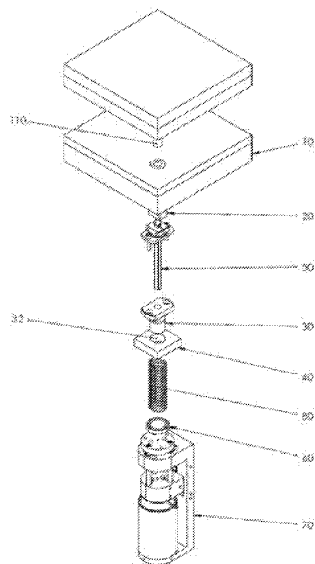


FIG. 1A

(57) **Abstract:** An ejecting system for a workpiece from a die cavity in a stamping machine is disclosed. The ejecting system has a spring plunger mechanism to fetch the workpiece from the die cavity of the die platen of the stamping machine. The spring plunger mechanism is provided with a picker which is integrated with a vacuum system to hold the workpiece. Underneath the spring plunger mechanism, there is an actuator, including a positioning sensor, for triggering both synchronous upward and downward movement of the linear actuator to the punch of a die set.

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